



CYPRESS

PAL22V10C PAL22VP10C

Universal PAL® Device

Features

- Ultra high speed supports today's and tomorrow's fastest microprocessors
 - $t_{PD} = 6 \text{ ns}$
 - $t_S = 3 \text{ ns}$
 - $f_{MAX} = 117 \text{ MHz}$
- Reduced ground bounce and undershoot
- PLCC and LCC packages with additional V_{CC} and V_{SS} pins for lowest ground bounce
- Up to 22 inputs and 10 outputs for more logic power
- Variable product terms
 - 8 to 16 per output

- 10 user-programmable output macrocells
 - Output polarity control
 - Registered or combinatorial operation
 - 2 new feedback paths (PAL22VP10C)
- Synchronous PRESET, asynchronous RESET, and PRELOAD capability for flexible design and testability
- High reliability
 - Proven Ti-W fuse technology
 - AC and DC tested at the factory
- Security Fuse

Functional Description

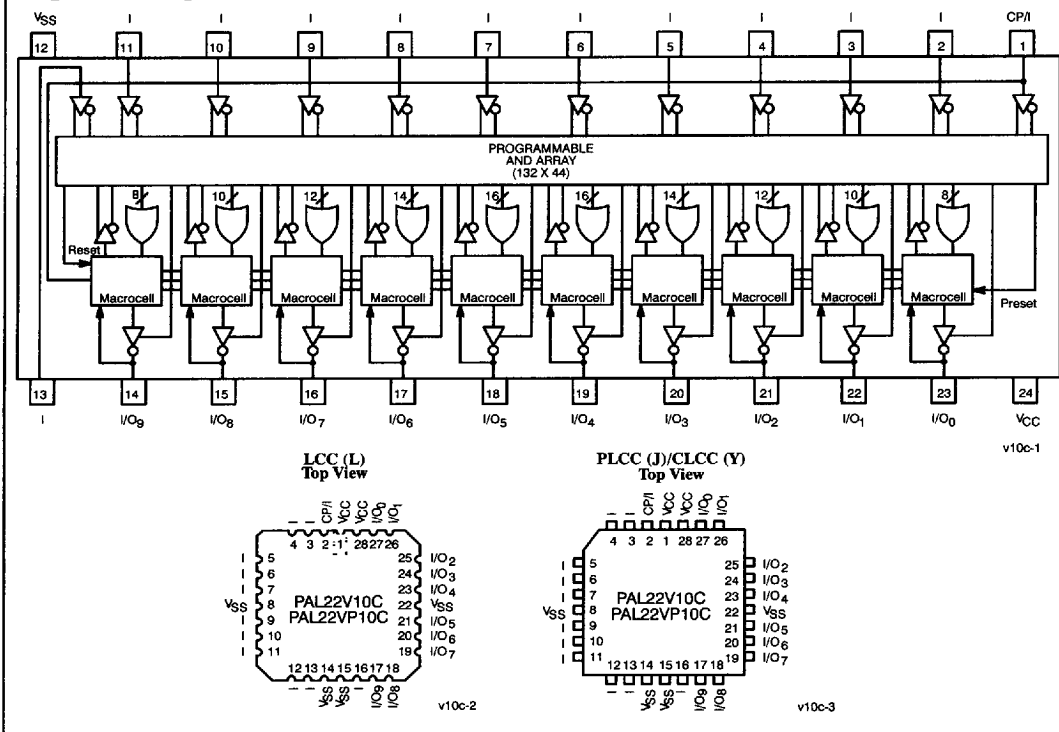
The Cypress PAL22V10C and PAL22VP10C are second-generation programmable array logic devices. Using

BiCMOS process and Ti-W fuses, the PAL22V10C and PAL22VP10C use the familiar sum-of-products (AND-OR) logic structure and a new concept, the programmable macrocell.

Both the PAL22V10C and PAL22VP10C provide 12 dedicated input pins and 10 I/O pins (see Logic Block Diagram). By selecting each I/O pin as either permanent or temporary input, up to 22 inputs can be achieved. Applications requiring up to 21 inputs and a single output, down to 12 inputs and 10 outputs can be realized. The output enable product term available on each I/O allows this selection.

The PAL22V10C and PAL22VP10C feature variable product term architecture, where 8 to 16 product terms are allocated to each output. This structure permits more applications to be implemented with

Logic Block Diagram and PDIP (P)/CDIP (D) and Pin Configurations



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Functional Description (continued)

these devices than with other PAL devices that have fixed number of product terms for each output.

Additional features include common synchronous preset and asynchronous reset product terms. They eliminate the need to use standard product terms for initialization functions.

Both the PAL22V10C and PAL22VP10C automatically reset on power-up. In addition, the preload capability allows the output registers to be set to any desired state during testing.

A security fuse is provided on each of these two devices to prevent copying of the device fuse pattern.

With the programmable macrocells and variable product term architecture, the PAL22V10C and PAL22VP10C can implement logic functions in the 700 to 800 gate array complexity, with the inherent advantages of programmable logic.

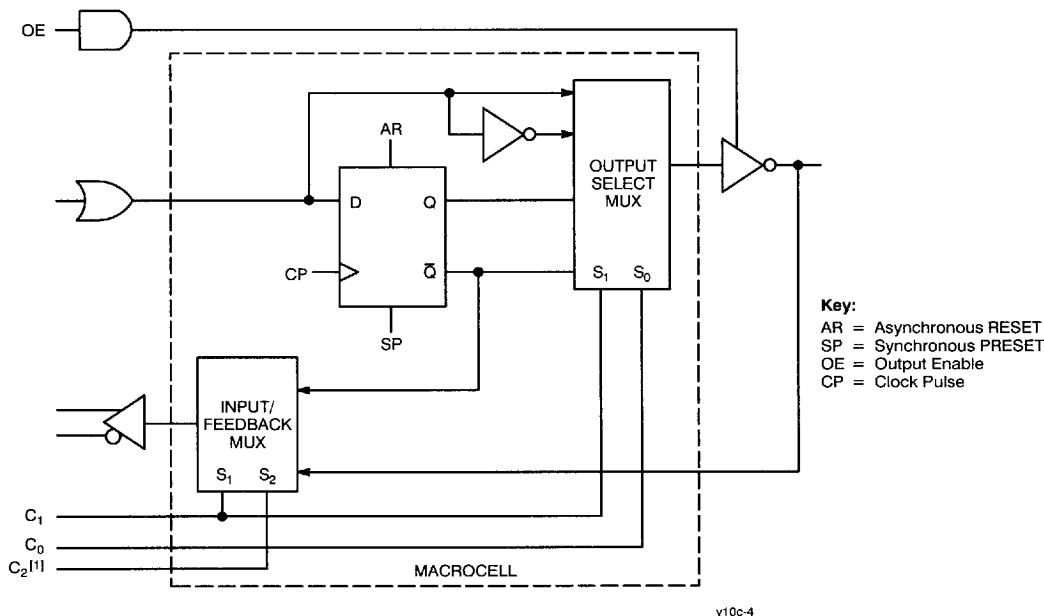
Programmable Macrocell

The PAL22V10C and PAL22VP10C each has 10 programmable output macrocells (see Macrocell figure). On the PAL22V10C two fuses (C_1 and C_0) can be programmed to configure output in one of four ways. Accordingly, each output can be registered or combinatorial with an active HIGH or active LOW polarity. The feedback to the array is also from this output (see Figure 1). An additional fuse (C_2) in the PAL22VP10C provides for two feedback paths (see Figure 2).

Programming

The PAL22V10C and PAL22VP10C can be programmed using the QuickPro II programmer available from Cypress Semiconductor and also with Data I/O, Logical Devices, STAG and other programmers. Please contact your local Cypress representative for further information.

Macrocell



Output Macrocell Configuration

$C_2[1]$	C_1	C_0	Output Type	Polarity	Feedback
0	0	0	Registered	Active LOW	Registered
0	0	1	Registered	Active HIGH	Registered
X	1	0	Combinatorial	Active LOW	I/O
X	1	1	Combinatorial	Active HIGH	I/O
1	0	0	Registered	Active LOW	I/O ^[1]
1	0	1	Registered	Active HIGH	I/O ^[1]

Note:

1. PAL22VP10C only.

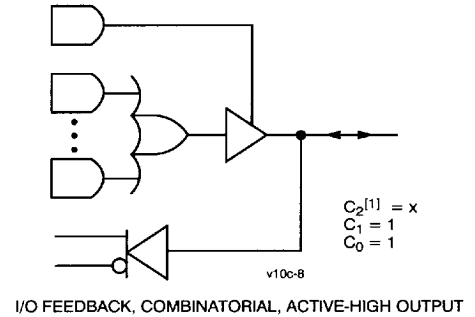
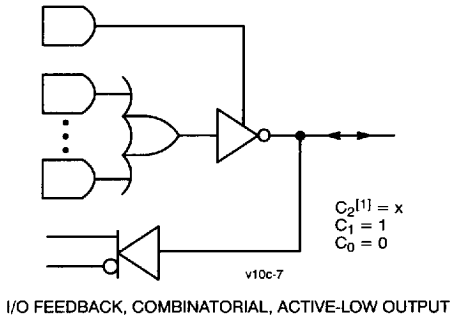
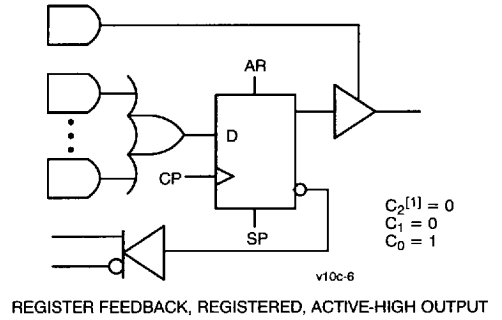
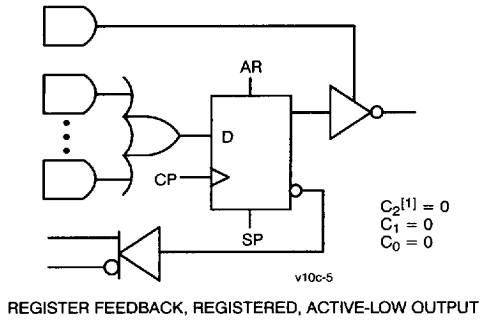


Figure 1. PAL22V10C and PAL22VP10C Macrocell Configurations

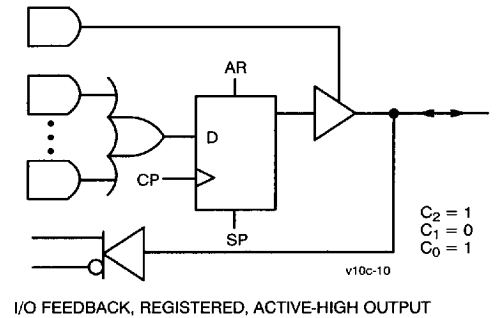
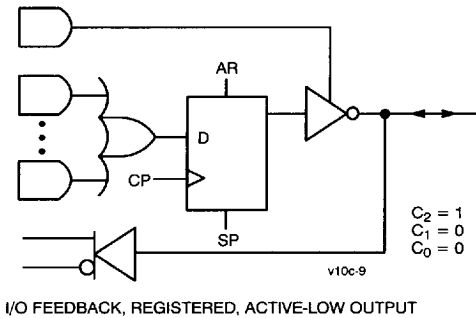


Figure 2. Additional Macrocell Configurations for the PAL22VP10C

Selection Guide

		22V10C-6 22VP10C-6	22V10C-7 22VP10C-7	22V10C-10 22VP10C-10	22V10C-12 22VP10C-12	22V10C-15 22VP10C-15
I _{CC} (mA)	Commercial	190	190	190	190	
	Military			190	190	190
t _{PD} (ns)	Commercial	6.0	7.5	10	12	
	Military			10	12	15
t _S (ns)	Commercial	3.0	3.0	3.6	4.5	
	Military			3.6	4.5	7.5
t _{CO} (ns)	Commercial	5.5	6.0	7.5	9.5	
	Military			7.5	9.5	10
f _{MAX} (MHz)	Commercial	117	111	90	71	
	Military			90	71	57

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature -65°C to +150°C

Ambient Temperature with

Power Applied -55°C to +125°C

Supply Voltage to Ground Potential -0.5V to +7.0V

DC Voltage Applied to Outputs

in High Z State -0.5V to V_{CC}

DC Input Voltage -0.5V to V_{CC}

DC Input Current -30 mA to +5 mA
(except during programming)

DC Program Voltage 10.0 V

Operating Range

Range	Ambient Temperature	V _{CC}
Commercial	0°C to +70°C	5V ± 5%
Military ^[2]	-55°C to +125°C	5V ± 5%

DC Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions		Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	V _{CC} = Min., V _{IN} = V _{IH} or V _{IL}	I _{OH} = -3.2 mA Com'l I _{OH} = -2 mA Mil	2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., V _{IN} = V _{IH} or V _{IL}	I _{OL} = 16 mA Com'l I _{OL} = 12 mA Mil		0.5	V
V _{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for All Inputs ^[3]		2.0		V
V _{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for All Inputs ^[3]			0.8	V
I _{IX}	Input Leakage Current	V _{SS} ≤ V _{IN} ≤ 2.7V, V _{CC} = Max.		-250	50	μA
I _I	Maximum Input Current	V _{IN} = V _{CC} , V _{CC} = Max.	Com'l Mil		100 250	μA
I _{OZ}	Output Leakage Current	V _{CC} = Max., V _{SS} ≤ V _{OUT} ≤ V _{CC}		-100	100	μA
I _{SC}	Output Short Circuit Current	V _{CC} = Max., V _{OUT} = 0.5V ^[4]		-30	-120	mA
I _{CC}	Power Supply Current	V _{CC} = Max., V _{IN} = GND, Outputs Open	Com'l Mil		190 190	mA

Capacitance^[5]

Parameter	Description	Max.	Unit
C _{IN}	Input Capacitance	8	pF
C _{OUT}	Output Capacitance	10	pF

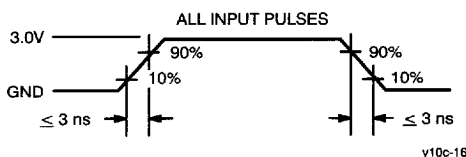
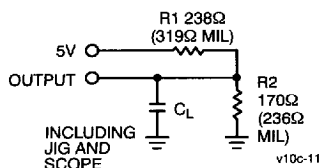
Notes:

1. t_A is the "instant on" case temperature.
2. These are absolute values with respect to device ground. All overshoots due to system or tester noise are included.
3. Not more than one output should be tested at a time. Duration of the short circuit should not be more than one second. V_{OUT} = 0.5V has

been chosen to avoid test problems caused by tester ground degradation.

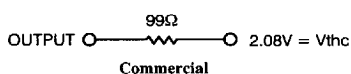
5. Tested initially and after any design or process changes that may affect these parameters.

AC Test Loads and Waveforms

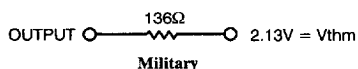


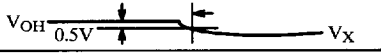
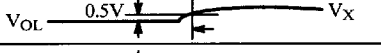
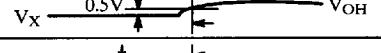
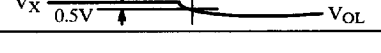
$C_L^{[6]}$	Package
15 pF ^[7]	P/D
50 pF	J/K/L/Y

Equivalent to: THÉVENIN EQUIVALENT



Equivalent to: THÉVENIN EQUIVALENT



Parameter	V_X	Output Waveform—Measurement Level
$t_{ER}(-)$	1.5V	
$t_{ER}(+)$	2.6V	
$t_{EA}(+)$	1.5V	
$t_{EA}(-)$	1.5V	

Notes:

6. $C_L = 5$ pF for t_{ER} measurement for all packages.

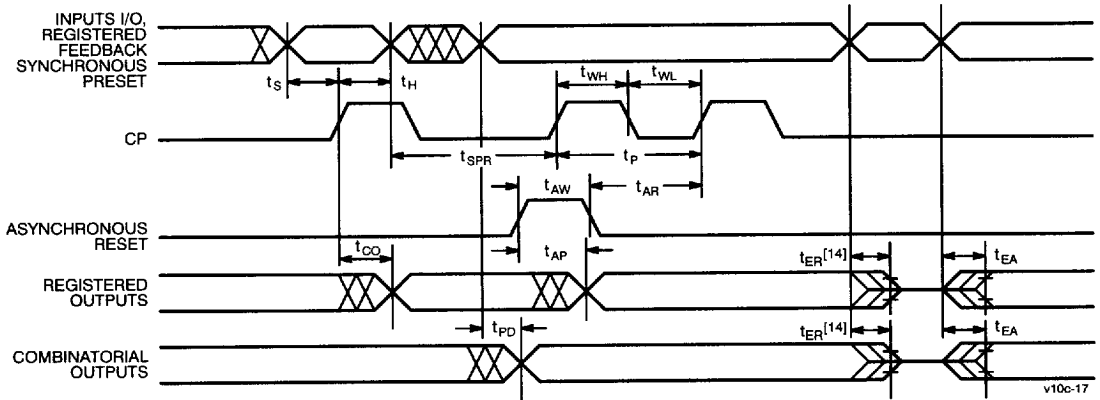
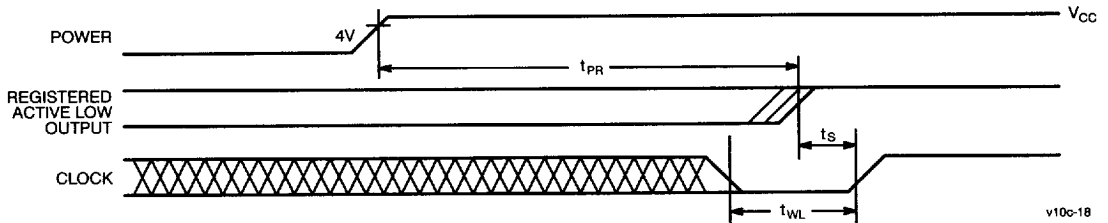
7. For high-capacitive load applications ($C_L = 50$ pF), use PAL22V10G/PAL22VP10G.

Switching Characteristics^[8]

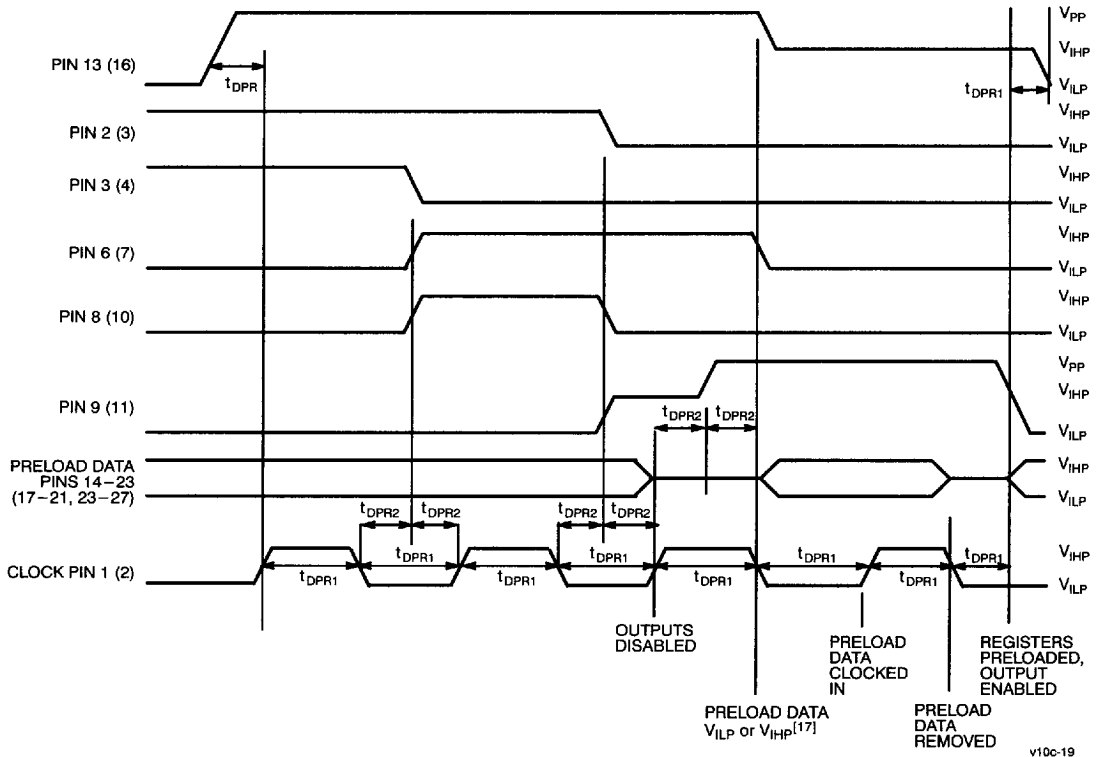
Parameter	Description	22V10C-6 22VP10C-6		22V10C-7 22VP10C-7		22V10C-10 22VP10C-10		22V10C-12 22VP10C-12		22V10C-15 22VP10C-15		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{PD}	Input to Output Propagation Delay ^[9]	1	6	2	7.5	2	10	2	12	2	15	ns
t_{EA}	Input to Output Enable Delay	1	6	2	7.5	2	10	2	12	2	15	ns
t_{ER}	Input to Output Disable Delay ^[10]	1	6	2	7.5	2	10	2	12	2	15	ns
t_{CO}	Clock to Output Delay ^[9]	1	5.5	1	6.0	1	7.5	1	9.5	1	10	ns
t_S	Input or Feedback Set-Up Time	3		3		3.6		4.5		7.5		ns
t_H	Input Hold Time	0		0		0		0		0		ns
t_P	External Clock Period ($t_{CO} + t_S$)	8.5		9		11.1		14		17.5		ns
t_{WH}	Clock Width HIGH ^[5]	3		3		3		3		6		ns
t_{WL}	Clock Width LOW ^[5]	3		3		3		3		6		ns
f_{MAX1}	External Maximum Frequency ($1/(t_{CO} + t_S)$) ^[11]	117		111		90		71		57		MHz
f_{MAX2}	Data Path Maximum Frequency ($1/(t_{WH} + t_{WL})$) ^[5, 12]	166		166		166		166		83		MHz
f_{MAX3}	Internal Feedback Maximum Frequency ($1/(t_{CF} + t_S)$) ^[13]	142		133		100		83		66		MHz
t_{CF}	Register Clock to Feedback Input ^[14]		4		4.5		6.4		7.5		7.5	ns
t_{AW}	Asynchronous Reset Width	7.5		8.5		10		12		15		ns
t_{AR}	Asynchronous Reset Recovery Time	4		5		6		7		10		ns

Switching Characteristics^[8]

Parameter	Description	22V10C-6 22VP10C-6		22V10C-7 22VP10C-7		22V10C-10 22VP10C-10		22V10C-12 22VP10C-12		22V10C-15 22VP10C-15		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t_{AP}	Asynchronous Reset to Registered Output Delay	2	11	2	12	2	12	2	14	2	20	ns
t_{SPR}	Synchronous Preset Recovery Time	4		5		6		7		10		ns
t_{PR}	Power-Up Reset Time ^[15]	1		1		1		1		1		μ s

Switching Waveform

Power-Up Reset Waveform^[15]

Notes:

- AC test load used for all parameters except where noted.
- This specification is guaranteed for all device outputs changing state in a given access cycle.
- This parameter is measured as the time after output disable input that the previous output data state remains stable on the output. This delay is measured to the point at which a previous HIGH level has fallen to 0.5 volts below V_{OH} min. or a previous LOW level has risen to 0.5 volts above V_{OL} max.
- This specification indicates the guaranteed maximum frequency at which a state machine configuration with external feedback can operate.
- This specification indicates the guaranteed maximum frequency at which an individual output register can be cycled.
- This specification indicates the guaranteed maximum frequency at which a state machine configuration with internal only feedback can operate. This parameter is tested periodically by sampling production product.
- This parameter is calculated from the clock period at f_{MAX} internal (f_{MAX3}) as measured (see Note 13) minus t_s .
- The registers in the PAL22V10C/PAL22VP10C have been designed with the capability to reset during system power-up. Following power-up, all registers will be reset to a logic LOW state. The output state will depend on the polarity of the output buffer. This feature is useful in establishing state machine initialization. To insure proper operation, the rise in V_{CC} must be monotonic and the timing constraints depicted in power-up reset waveforms must be satisfied.

Preload Waveform^[16]


v10c-19

D/K/P (J/L/Y) Pinouts

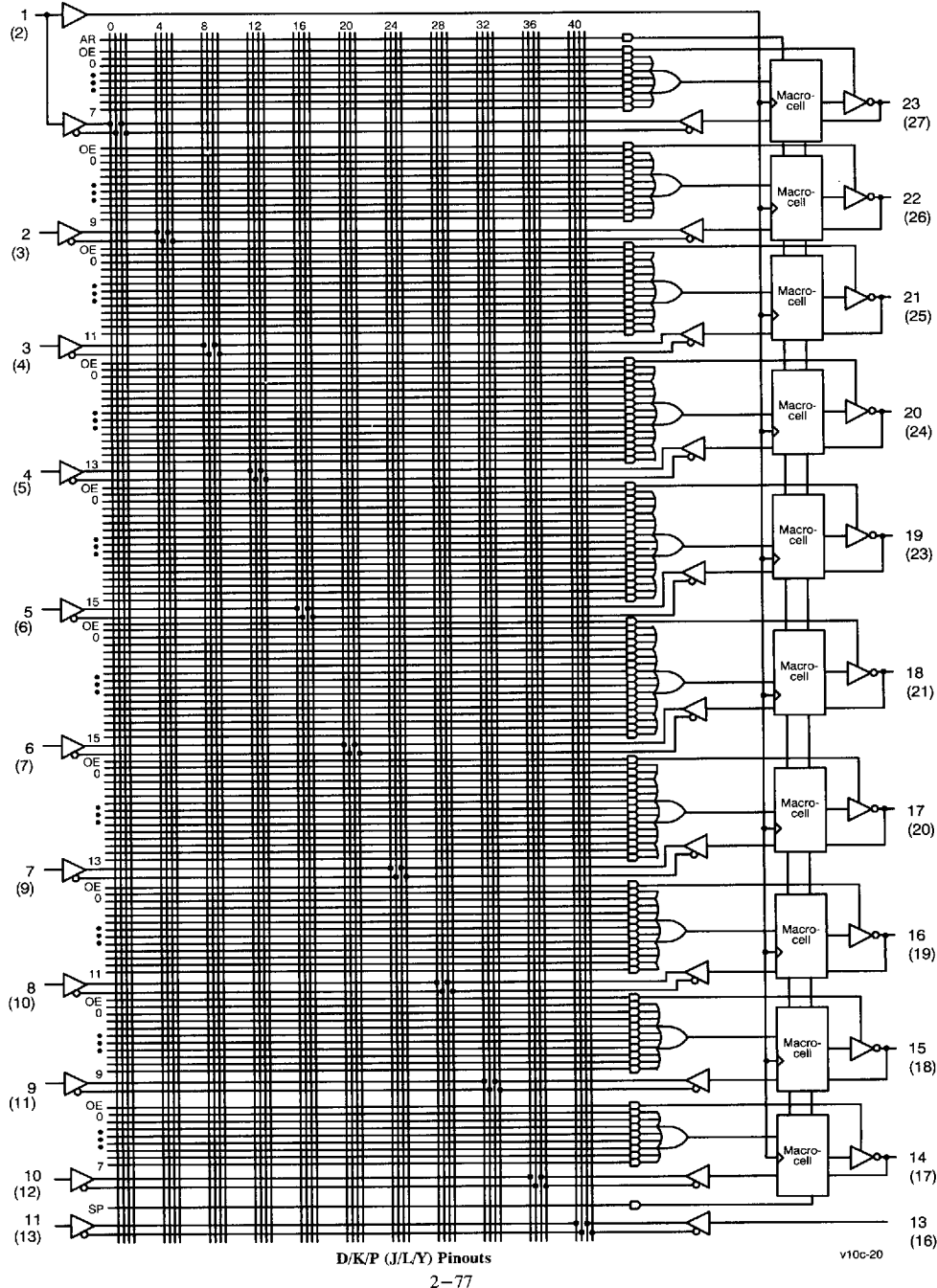
Forced Level on Register Pin During Preload	Register Q Output State After Preload
V _{IHP}	HIGH
V _{ILP}	LOW

Name	Description	Min.	Max.	Unit
V _{PP}	Programming Voltage	9.25	9.75	V
t _{DPR1}	Delay for Preload	1		μs
t _{DPR2}	Delay for Preload	0.5		μs
V _{ILP}	Input LOW Voltage	0	0.4	V
V _{IHP}	Input HIGH Voltage	3	4.75	V
V _{CCP}	V _{CC} for Preload	4.75	5.25	V

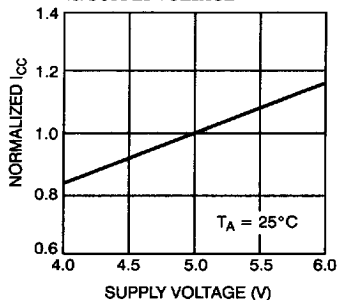
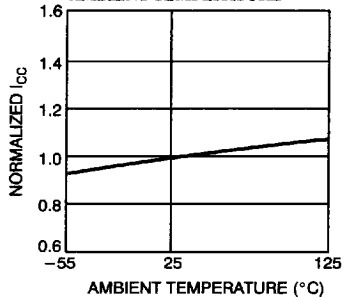
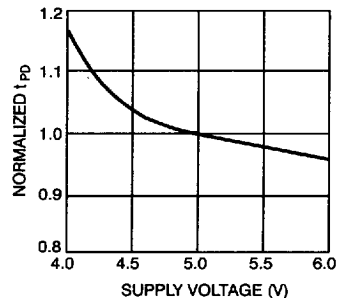
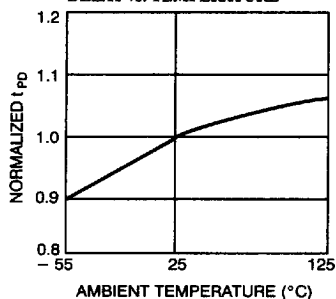
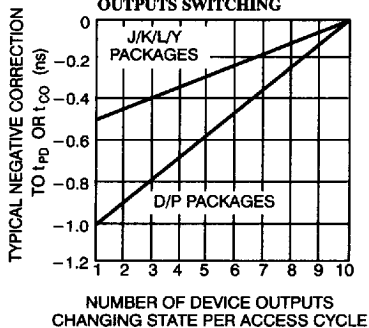
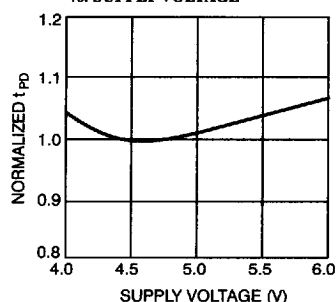
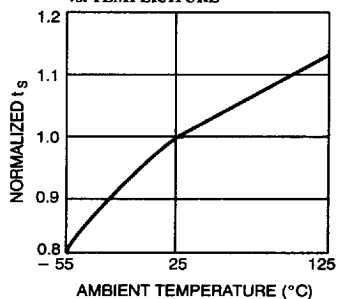
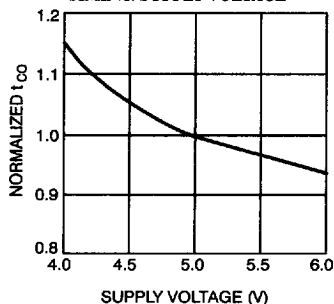
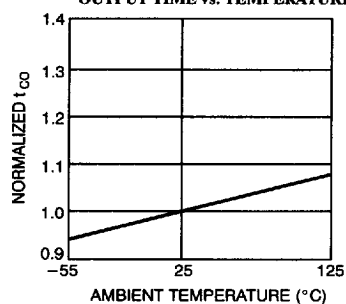
Notes: (The numbers in parenthesis are for the J, L, and Y pins).

16. Pins 4 (5), 5 (6), 7 (9) at V_{ILP}; Pins 10 (12) and 11 (13) at V_{IHP}; V_{CC} (Pin 24 (1 and 28)) at V_{CCP}

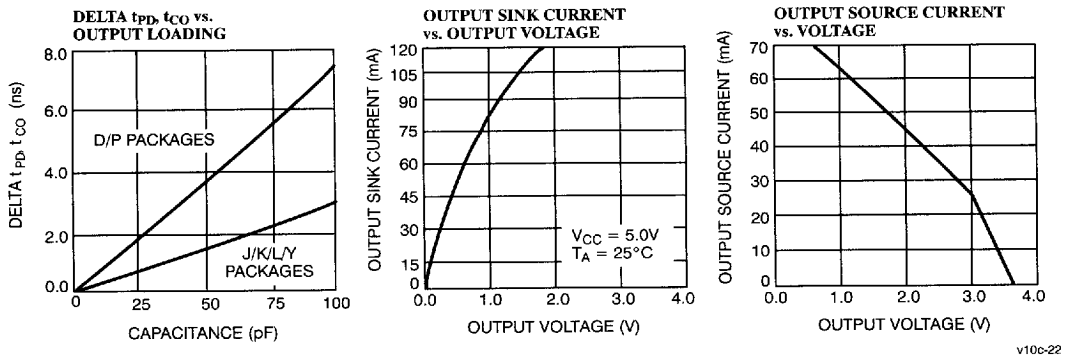
17. Pins 2-8 (3-7, 9, 10), 10 (12), 11 (13) can be set at V_{IHP} or V_{ILP} to insure asynchronous reset is not active.

Functional Logic Diagram for PAL22V10C/PAL22VP10C


2589662 0012978 159

Typical DC and AC Characteristics
**NORMALIZED SUPPLY CURRENT
vs. SUPPLY VOLTAGE**

**NORMALIZED SUPPLY CURRENT vs.
AMBIENT TEMPERATURE**

**NORMALIZED PROPAGATION
DELAY vs. SUPPLY VOLTAGE**

**NORMALIZED PROPAGATION
DELAY vs. TEMPERATURE**

**TYPICAL CORRECTION TO t_{PD}
AND t_{CO} vs. NUMBER OF
OUTPUTS SWITCHING**

**NORMALIZED SET-UP TIME
vs. SUPPLY VOLTAGE**

**NORMALIZED SET-UP TIME
vs. TEMPERATURE**

**NORMALIZED CLOCK TO OUTPUT
TIME vs. SUPPLY VOLTAGE**

**NORMALIZED CLOCK TO
OUTPUT TIME vs. TEMPERATURE**


v10c-21

Typical DC and AC Characteristics (continued)

Ordering Information

I_{CC} (mA)	t_{PD} (ns)	f_{MAX} (MHz)	Ordering Code	Package Name	Package Type	Operating Range
190	6	117	PAL22V10C-6JC	J64	28-Lead Plastic Leaded Chip Carrier	Commercial
			PAL22V10C-7DC	D14	24-Lead (300-Mil) CerDIP	Commercial
			PAL22V10C-7JC	J64	28-Lead Plastic Leaded Chip Carrier	
			PAL22V10C-7PC	P13	24-Lead (300-Mil) Molded DIP	
			PAL22V10C-7YC	Y64	28-Pin Ceramic Leaded Carrier	
	10	90	PAL22V10C-10DC	D14	24-Lead (300-Mil) CerDIP	Commercial
			PAL22V10C-10JC	J64	28-Lead Plastic Leaded Chip Carrier	
			PAL22V10C-10PC	P13	24-Lead (300-Mil) Molded DIP	
			PAL22V10C-10YC	Y64	28-Pin Ceramic Leaded Carrier	
			PAL22V10CM-10DMB	D14	24-Lead (300-Mil) CerDIP	Military
			PAL22V10CM-10KMB	K73	24-Lead Rectangular Cerpack	
			PAL22V10CM-10LMB	L64	28-Square Leadless Chip Carrier	
			PAL22V10CM-10YMB	Y64	28-Pin Ceramic Leaded Carrier	
	12	71	PAL22V10C-12DC	D14	24-Lead (300-Mil) CerDIP	Commercial
			PAL22V10C-12JC	J64	28-Lead Plastic Leaded Chip Carrier	
			PAL22V10C-12PC	P13	24-Lead (300-Mil) Molded DIP	
			PAL22V10C-12YC	Y64	28-Pin Ceramic Leaded Carrier	
			PAL22V10CM-12DMB	D14	24-Lead (300-Mil) CerDIP	Military
			PAL22V10CM-12KMB	K73	24-Lead Rectangular Cerpack	
			PAL22V10CM-12LMB	L64	28-Square Leadless Chip Carrier	
			PAL22V10CM-12YMB	Y64	28-Pin Ceramic Leaded Carrier	
	15	57	PAL22V10CM-15DMB	D14	24-Lead (300-Mil) CerDIP	Military
			PAL22V10CM-15KMB	K73	24-Lead Rectangular Cerpack	
			PAL22V10CM-15LMB	L64	28-Square Leadless Chip Carrier	
			PAL22V10CM-15YMB	Y64	28-Pin Ceramic Leaded Carrier	



Ordering Information (continued)

I _{CC} (mA)	t _{PD} (ns)	f _{MAX} (MHz)	Ordering Code	Package Type		Operating Range
190	6	117	PAL22VP10C-6JC	J64	28-Lead Plastic Leaded Chip Carrier	Commercial
		7.5	111	PAL22VP10C-7DC	D14	24-Lead (300-Mil) CerDIP
	PAL22VP10C-7JC			J64	28-Lead Plastic Leaded Chip Carrier	
	PAL22VP10C-7PC			P13	24-Lead (300-Mil) Molded DIP	
	PAL22VP10C-7YC			Y64	28-Pin Ceramic Leaded Carrier	
	10	90	PAL22VP10C-10DC	D14	24-Lead (300-Mil) CerDIP	Commercial
			PAL22VP10C-10JC	J64	28-Lead Plastic Leaded Chip Carrier	
			PAL22VP10C-10PC	P13	24-Lead (300-Mil) Molded DIP	
			PAL22VP10C-10YC	Y64	28-Pin Ceramic Leaded Carrier	
			PAL22VP10CM-10DMB	D14	24-Lead (300-Mil) CerDIP	Military
			PAL22VP10CM-10KMB	K73	24-Lead Rectangular Cerpack	
			PAL22VP10CM-10LMB	L64	28-Square Leadless Chip Carrier	
			PAL22VP10CM-10YMB	Y64	28-Pin Ceramic Leaded Carrier	
	12	71	PAL22VP10C-12DC	D14	24-Lead (300-Mil) CerDIP	Commercial
			PAL22VP10C-12JC	J64	28-Lead Plastic Leaded Chip Carrier	
			PAL22VP10C-12PC	P13	24-Lead (300-Mil) Molded DIP	
			PAL22VP10C-12YC	Y64	28-Pin Ceramic Leaded Carrier	
			PAL22VP10CM-12DMB	D14	24-Lead (300-Mil) CerDIP	Military
			PAL22VP10CM-12KMB	K73	24-Lead Rectangular Cerpack	
			PAL22VP10CM-12LMB	L64	28-Square Leadless Chip Carrier	
			PAL22VP10CM-12YMB	Y64	28-Pin Ceramic Leaded Carrier	
	15	57	PAL22VP10CM-15DMB	D14	24-Lead (300-Mil) CerDIP	Military
			PAL22VP10CM-15KMB	K73	24-Lead Rectangular Cerpack	
			PAL22VP10CM-15LMB	L64	28-Square Leadless Chip Carrier	
			PAL22VP10CM-15YMB	Y64	28-Pin Ceramic Leaded Carrier	

MILITARY SPECIFICATIONS

Group A Subgroup Testing

DC Characteristics

Parameters	Subgroups
V _{OH}	1, 2, 3
V _{OL}	1, 2, 3
V _{IH}	1, 2, 3
V _{IL}	1, 2, 3
I _{IX}	1, 2, 3
I _{OZ}	1, 2, 3
I _{CC}	1, 2, 3

Switching Characteristics

Parameters	Subgroups
t _{PD}	7, 8, 9, 10, 11
t _{CO}	7, 8, 9, 10, 11
t _S	7, 8, 9, 10, 11
t _H	7, 8, 9, 10, 11

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